

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.33836	100.0	0.77
Subtotal				0.33836	100	0.77
Post-plating	Tin solder	Bismuth (Bi)	7440-69-9	0	0.0	0
	Tin solder	Tin (Sn)	7440-31-5	1.61692	99.99	3.67963
	Tin solder	Copper (Cu)	7440-50-8	0	0.0	0
	Tin solder	Lead (Pb)	7439-92-1	0.00016	0.01	0.00037
	Tin solder	Antimony (Sb)	7440-36-0	0	0.0	0
Subtotal				1.61708	100	3.68
Lead Frame	Copper alloy	Misc. Phosphor compounds (generic)	7723-14-0	0.00789	0.02	0.01794
	Copper alloy	Iron (Fe)	7439-89-6	0.03154	0.08	0.07178
	Copper alloy	Copper (Cu)	7440-50-8	39.30696	99.7	89.45084
	Pure metal layer	Silver (Ag)	7440-22-4	0.07885	0.2	0.17944
Subtotal				39.42524	100	89.72
Adhesive	Polymer	Paraffin wax	8002-74-2	0.21971	20.0	0.5
	Polymer	Epoxy resin system		0.08789	8.0	0.2
	Filler	Silver (Ag)	7440-22-4	0.79097	72.0	1.8
Subtotal				1.09857	100	2.5
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	1.43769	2.5	3.27175
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.31307	7.5	9.81525
	Filler	Silica -amorphous-	7631-86-9	21.2778	37.0	48.4219
	Pigment	Carbon black	1333-86-4	0.28754	0.5	0.65435
	Polymer	Epoxy resin system		8.62614	15.0	19.6305
	Filler	Silicon Dioxide (SiO2)	14808-60-7	21.2778	37.0	48.4219
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.28754	0.5	0.65435
Subtotal				57.50758	100	130.87
Wire	Pure metal	Copper (Cu)	7440-50-8	0.01318	100.0	0.03
			Subtotal	0.01318	100	0.03
Total				100.00001	100	227.57

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